ADT
Advanced Dicing Technologies

8030 Dicing Saw

Fully Automatic Twin Dicing Saw

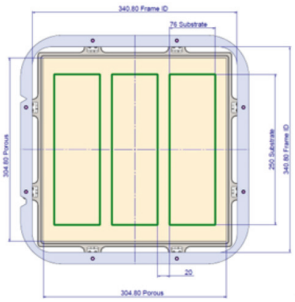
Configuration

- Blade O.D.: 2”-3”
- Size: 6”, 8", 12"

Features and Benefits

- Flexibility - Supports Hub and Hubless blades
- Dual microscopes, fixed non-contact sensors and two dress stations
- Spindles of 1.8 kW or 2.2 kW high power
- Superior vision system with continuous zoom magnification
- Intuitive operation interface using a large 19” touch screen monitor

3 Lead-Frames Square Chuck



Other Key Features of Importance

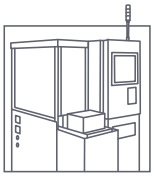
- Highest dicing process speeds
- Support up to 12” × 12” square products
- Industrial PC based on Win 10 OS
- Air bearing feed axis (X)
- Fast & Simple blade change with a spindle shaft lock mechanism
- Fast automatic alignment and cut positioning for increased throughput
- Automatic Kerf inspection and quality analysis for maximum precision
- Process data logging and statistical analysis
- SECS / GEM platform ready
- All electronic on top of the cut chamber

Ease of Use

The 8030 operates with the ADT intuitive New Graphic User Interface (NGUI) and includes two touch - screens: 19” monitor for the main screen and 17” monitor maintenance screen.

Leading Applications

- Silicon wafers for Memory and Logic products
- MEMS (micro-electromechanical system)
- CMOS Image Sensors (CIS)
- Packaging (FOPLP, FOWLP, QFN, BGA)



8030 Fully Automatic Twin Dicing Saw

Specifications

Workpiece Size	Ø 8", Ø 12" or 12" x 12" square
Spindle	Two facing 1.8 kW or 2.2 kW, max. 60,000 rpm
Blade Size	2" - 3"
Y1 / Y2 Axis:	
Drive	Ball bearing lead screw
Control	Linear encoder for each Y axis
Resolution	0.1 µm
Cumulative Accuracy	1.5 µm
Indexing Accuracy	1.0 µm
Cutting range	350 mm
X Axis:	Air Slide
Drive	Ball bearing lead screw
Feed rate	Up to 600 mm/sec (Optional for 1000 mm/sec)
Cutting range	310 mm
Z1 / Z2 Axis:	
Drive	Ball bearing lead screw
Resolution	0.2 µm
Repeatability	1.0 µm
Max. stroke	50 mm (for 2.188" blade OD)
θ Axis:	
Drive	Closed-loop, Direct-drive
Repeatability	4 arc-sec
Stroke	380°
Vision System	USB3 camera, High bright LED illumination (vertical & oblique)
Cleaning Station:	Full rinse and dry cycle
Spinning speed	100-3,000 rpm
Cleaning Method	Atomized cleaning capabilities
Wafer Handling system	Slot to slot integrity
Standard Features	Automatic alignment Automatic Cut verify Automatic Kerf inspection Automatic Y offset correction
User Interface	2 touch screens: 19" monitor as main screen and 17" monitor for maintenance NGUI (New Graphic User Interface) Multilanguage support Win 10 OS
Options	BBD (Broken Blade Detector) High power spindle up to 2.2KW at 60 KRPM Barcode reader UV station USB3 camera with Continuous Digital Magnification from x70 to x290 Dress station ESD Kit High Definition Optics Geometric Model Finder (GMF) Dicing Floor Management (SECS/GEM) Customization
Utilities:	
Electrical	200-240 VAC, 50/60 Hz, single phase
Air	500 L/min @ 5.5 bar
Spindle Coolant (per spindle)	1.1 L/min
Cutting water (per spindle)	Up to 3 L/min
Dimensions:	
WxDxH	1145 mm × 1687 mm × 1830 mm
Weight	1500 kg
Environmental	Room Temperature: 20°C to 25°C ± 1°C (77°F ± 1.8°F) Humidity: Less than 70% relative humidity (non-condensing) Cutting water / Spindle Water, Temperature ± 1°C (± 1.8°F) Floor must be vibration free

Note: Specifications are subject to change without notice.

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